

IN THE CLAIMS:

Please amend claims 13 and 21 as follows:

LISTING OF CURRENT CLAIMS

Claims 1-12. (Canceled)

Claim 13. (Currently Amended) A multi-chip package combining wire-bonding and flip-chip configuration comprising:

- 5 a) a substrate having an upper substrate surface and a ~~substrate~~ lower substrate surface, the upper substrate surface having a plurality of contact pads;
- b) at least one wire bonding chip connected to the upper substrate surface and electrically connected to the substrate by a plurality of bonding wires;
- 10 c) a molding compound formed on the upper substrate surface covering each of the at least one wire bonding chip and the plurality of bonding wires, the molding compound having:
 - i) two extensions; and
 - ii) at least one recession located between the two extensions, the ~~at least one recession~~ two extensions being spaced apart from
 - 15 the plurality of contact pads; and
- d) at least one flip-chip electrical device having a plurality of bumps electrically connected to the plurality of contact pads of the substrate.

Claim 14. (Previously Presented) The multi-chip package according to claim 13, wherein the distance between the at least one recession and a closest contact pad of the plurality of contact pads is greater than 1.0mm.

Claim 15. (Previously Presented) The multi-chip package according to claim 13, wherein the at least one recession has an arc shape.

Claim 16. (Previously Presented) The multi-chip package according to claim 13, wherein the at least one recession has a shape of a quarter of a circle.

Claim 17. (Previously Presented) The multi-chip package according to claim 13, wherein the at least one recession includes two recessions, the two recessions are symmetrical.

Claim 18. (Previously Presented) The multi-chip package according to claim 13, wherein the molding compound has an U-shape.

Claim 19. (Previously Presented) The multi-chip package according to claim 13, wherein the molding compound has an L-shape.

Claim 20. (Previously Presented) The multi-chip package according to claim 13, wherein the at least one flip-chip electrical device is selected from a group consisting of a BGA package, a chip scale package, and a flip chip.

Claim 21. (Currently Amended) The multi-chip package according to claim 13, further comprising a plurality of solder balls located on the ~~substrate~~ lower substrate surface.

Claim 22. (Previously Presented) The multi-chip package according to claim 13, further comprising a heat sink connected to the molding compound and the at least one flip-chip electrical device.

Claim 23. (Previously Presented) The multi-chip package according to claim 13, wherein the molding compound has at least one step located on a surface opposite the substrate.

Claim 24. (Previously Presented) The multi-chip package according to claim 13, wherein the molding compound has at least one indentation located on a surface opposite the substrate.

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Claim 25. (Previously Presented) The multi-chip package according to claim 13, wherein the substrate has a molding gate metal layer.